

# LM25137F 4V to 42V, 100% Duty Cycle Capable, Dual-Channel, Synchronous Buck DC/DC Controller Family for Functional Safety Applications

## 1 Features

- **Functional Safety-Compliant**
  - Developed for functional safety applications
    - Three [orderable part numbers](#) for Capable, SIL 2, and SIL 3 options
  - Documentation available to aid IEC 61508 systems design up to SIL 3 per IEC TR 62380
  - Systematic capability up to SIL 3
  - Random fault integrity up to SIL 3
- Versatile dual synchronous buck DC/DC controller
  - Wide input voltage range of 4V to 42V
  - 1% accurate, fixed 3.3V, 5V, 12V, or adjustable outputs from 0.8V to 36V
  - Current monitor output for each channel
  - Charge-pump gate drivers for 100% duty cycle
  - Sleep quiescent current of 1.8µA (typical)
  - Internal hiccup-mode overcurrent protection
- Two interleaved synchronous buck channels
  - Dual channel or single-output multiphase
  - Stackable up to four phases
  - SYNC in and SYNC out capability
  - Selectable light-load PFM or FPWM
  - 22ns  $t_{ON(min)}$  for high  $V_{IN}/V_{OUT}$  ratio
- Designed for ultra-low EMI requirements
  - Dual Random Spread Spectrum (DRSS)
  - Switching frequency from 100kHz to 2.64MHz
- VQFN-36 [package](#) with wettable flanks
- Create a custom design using the LM25137F with the [WEBENCH® Power Designer](#)

## 2 Applications

- **Personal electronics:** computer peripherals
- **Industrial:** 24V bus systems, power delivery
- **Enterprise systems:** high-performance computing

## 3 Description

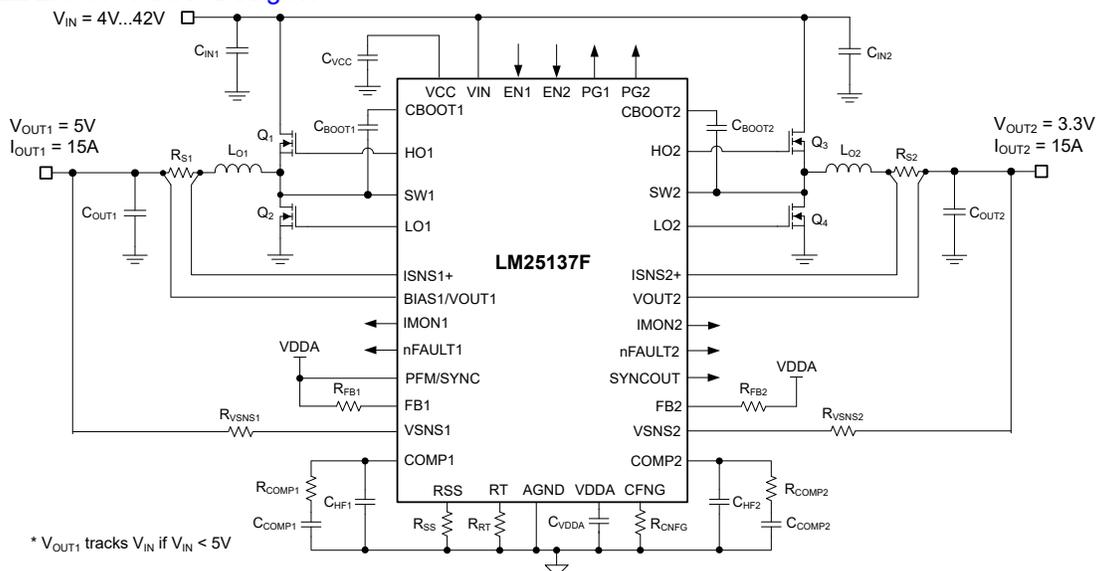
The LM25137F is a 42V, dual-channel, buck controller offered from a family with three [options](#) for functional safety: Capable, SIL 2, or SIL 3. The device uses an interleaved, stackable, peak current-mode architecture for easy loop compensation, fast transient response, excellent load and line regulation, and accurate current sharing with paralleled phases for high output current. A high-side switch minimum on-time of 22ns facilitates large step-down ratios, enabling the direct conversion from 12V and 24V inputs to low-voltage rails for reduced system design cost and complexity. The LM25137F continues to operate during input voltage dips as low as 4V, at 100% duty cycle if needed.

### Package Information

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>
LM25137F	RHA (VQFN, 36)	6.0mm × 6.0mm

(1) For more information, see [Section 7](#).

(2) The package size (length × width) is a nominal value and includes pins, where applicable.



LM25137F Dual-Output Buck Switching Regulator – Simplified Schematic



Several features are included to simplify compliance with CISPR 11 and CISPR 32 EMI requirements. Adaptively timed, high-current MOSFET gate drivers minimize body diode conduction during switching transitions, reducing switching losses and improving thermal and EMI performance at high input voltage and high switching frequency. To reduce input capacitor ripple current and EMI filter size, 180° interleaved operation is provided for two outputs. A 90° out-of-phase clock output works well for cascaded, multi-channel or multiphase power stages. Resistor-adjustable switching frequency as high as 2.2MHz can be synchronized to an external clock source up to 2.64MHz to eliminate beat frequencies in noise-sensitive applications.

The 1.8μA sleep quiescent current with the output voltage in regulation extends operating run-time in battery-powered systems. Additional features of the LM25137F include 150°C maximum junction temperature operation, user-selectable PFM mode for lower current consumption at light-load conditions, configurable soft-start functions, open-drain FAULT and PG flags for fault reporting and output monitoring, independent enable inputs, monotonic start-up into prebiased loads, integrated VCC bias supply regulator powered from VIN or VOUT1, hiccup-mode overload protection, and thermal shutdown protection with automatic recovery. Current is sensed using an optional shunt resistor for high accuracy. Specific features for functional safety applications, including ABIST at start-up, VOUT1/2 and VCC ripple detection, redundant bandgap with error monitoring, redundant and fast VOUT1/2 monitoring, feedback path failure detection, and redundant thermal shutdown significantly reduces FIT rate.

The LM25137F controller comes in a 6mm × 6mm thermally-enhanced, 36-pin VQFN package with additional pin clearance for increased reliability. Also included are wettable flank pins to facilitate optical inspection during manufacturing. The wide input voltage range, low quiescent current consumption, high-temperature operation, cycle-by-cycle current limit, low EMI signature, and [small design size](#) provide an excellent point-of-load regulator design for functional safety (FuSa) applications requiring enhanced robustness and durability.

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## 4 Related Products

**Table 4-1. Orderable Part Numbers**

GENERIC PART NUMBER	ORDERABLE PART NUMBER	TI FUNCTIONAL SAFETY CLASSIFICATION <sup>(1)</sup>	PRODUCT DATA SHEET
<a href="#">LM25137</a>	LM25137RHAR	Functional safety-capable	Available <a href="#">here</a>
<a href="#">LM25137F</a>	LM25137F2RHAR	SIL 2 functional safety-compliant	Request the full data sheet <a href="#">here</a>
	LM25137F3RHAR	SIL 3 functional safety-compliant	

- (1) Refer to the [functional safety homepage](#) to understand the TI functional safety classifications (in terms of the development process, analysis report, and diagnostics description).

## 5 Device and Documentation Support

### 5.1 Device Support

#### 5.1.1 Third-Party Products Disclaimer

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#### 5.1.2 Development Support

With an input operating voltage as low as 3.5V and up to 100V as specified in [Table 5-1](#), the family of synchronous buck controllers from TI provides flexibility, scalability, and optimized design size for a variety of applications.

With the LM5137F and LM25137F available to aid in functional safety system design up to SIL 3, the controller family enables DC/DC designs with high density, low EMI, and increased system reliability.

**Table 5-1. Synchronous Buck DC/DC Controller Family**

DC/DC CONTROLLER	SINGLE or DUAL	V <sub>IN</sub> RANGE	CONTROL METHOD	GATE DRIVE VOLTAGE	SYNC OUTPUT	KEY FEATURE
<a href="#">LM5137</a>	Dual	4V to 80V	Peak current mode	5V	90° phase shift	100% duty cycle
<a href="#">LM5137F</a>	Dual	4V to 80V	Peak current mode	5V	90° phase shift	SIL 2 or 3
<a href="#">LM25137</a>	Dual	4V to 42V	Peak current mode	5V	90° phase shift	100% duty cycle
<a href="#">LM25137F</a>	Dual	4V to 42V	Peak current mode	5V	90° phase shift	SIL 2 or 3
<a href="#">LM25139</a>	Single	4V to 42V	Peak current mode	5V	N/A	DRSS
<a href="#">LM5141</a>	Single	3.8V to 65V	Peak current mode	5V	N/A	Split gate drive
<a href="#">LM25141</a>	Single	3.8V to 42V	Peak current mode	5V	N/A	Split gate drive
<a href="#">LM5143</a>	Dual	3.5V to 65V	Peak current mode	5V	90° phase shift	Split gate drive
<a href="#">LM25143</a>	Dual	3.5V to 42V	Peak current mode	5V	90° phase shift	Split gate drive
<a href="#">LM5145</a>	Single	5.5V to 75V	Voltage mode	7.5V	180° phase shift	No shunt
<a href="#">LM5146</a>	Single	5.5V to 100V	Voltage mode	7.5V	180° phase shift	100V input capability
<a href="#">LM5148</a>	Single	3.5V to 80V	Peak current mode	5V	180° phase shift	DRSS
<a href="#">LM25148</a>	Single	3.5V to 42V	Peak current mode	5V	180° phase shift	DRSS
<a href="#">LM5149</a>	Single	3.5V to 80V	Peak current mode	5V	180° phase shift	AEF
<a href="#">LM25149</a>	Single	3.5V to 42V	Peak current mode	5V	180° phase shift	AEF
<a href="#">LM5190</a>	Single	5V to 80V	Peak current mode	7.5V	N/A	CC/CV
<a href="#">LM25190</a>	Single	5V to 42V	Peak current mode	7.5V	N/A	CC/CV

For development support, see the following:

- [LM25137F DC/DC controller Quickstart Calculator](#) and [PSPICE](#) simulation models
- [LM5137F-Q1-EVM12V](#) and [LM25137F-Q1-EVM5D3 Altium layout source](#) files
- For TI's WEBENCH design environments, visit the [WEBENCH® Design Center](#)
- For TI's reference design library, visit [TI Designs](#)
- TI reference designs:
  - [450W four-phase interleaved buck converter reference design](#)
  - [20V<sub>IN</sub> to 60V<sub>IN</sub>, 600W, automotive two-phase buck regulator with GaN power switches reference design](#)

#### 5.1.2.1 Custom Design With WEBENCH® Tools

[Click here](#) to create a custom design using the LM25137F device with the WEBENCH® Power Designer.

1. Start by entering the input voltage (V<sub>IN</sub>), output voltage (V<sub>OUT</sub>), and output current (I<sub>OUT</sub>) requirements.
2. Optimize the design for key parameters such as efficiency, footprint, and cost using the optimizer dial.

- Compare the generated design with other possible solutions from Texas Instruments.

The WEBENCH Power Designer gives a customized schematic along with a list of materials with real-time pricing and component availability.

In most cases, these actions are available:

- Run electrical simulations to see important waveforms and circuit performance
- Run thermal simulations to understand board thermal performance
- Export customized schematic and layout into popular CAD formats
- Print PDF reports for the design, and share the design with colleagues

Get more information about WEBENCH tools at [www.ti.com/WEBENCH](http://www.ti.com/WEBENCH).

## 5.2 Documentation Support

### 5.2.1 Related Documentation

For related documentation, see the following:

- User's guides:
  - Texas Instruments, [LM5137F-Q1 12V, 20A Single-Output Evaluation Module](#)
  - Texas Instruments, [LM25137-Q1 Evaluation Module](#)
  - Texas Instruments, [LM5143-Q1 EVM User's Guide](#)
  - Texas Instruments, [LM5141-Q1 EVM User's Guide](#)
  - Texas Instruments, [LM5146-Q1 EVM User's Guide](#)
  - Texas Instruments, [LM5145EVM-HD-20A High Density Evaluation Module](#)
  - Texas Instruments, [LM5149-Q1 Buck Converter Evaluation Module User's Guide](#)
  - Texas Instruments, [LM5190-Q1 CC-CV Buck Controller Evaluation Module](#)
- Application notes:
  - Texas Instruments, [How to Implement a Four-Phase Interleaving Buck With the LM5137F-Q1](#)
  - Texas Instruments, [LM5143-Q1 4-phase Buck Regulator Design for Automotive ADAS Applications](#)
- Technical articles:
  - Texas Instruments, [Achieving functional safety compliance in automotive off-battery buck preregulator designs](#)
  - Texas Instruments, [Powering next-generation ADAS processors with TI Functional Safety-Compliant buck regulators](#)

#### 5.2.1.1 Low-EMI Design Resources

- Texas Instruments, [Low EMI](#) landing page
- Texas Instruments, [Tackling the EMI challenge](#) company blog
- Texas Instruments, [An Engineer's Guide to Low EMI in DC/DC Regulators](#) e-book
- Texas Instruments, [Designing a low-EMI power supply](#) video series
- White papers:
  - Texas Instruments, [An Overview of Conducted EMI Specifications for Power Supplies](#)
  - Texas Instruments, [An Overview of Radiated EMI Specifications for Power Supplies](#)
  - Texas Instruments, [Time-Saving and Cost-Effective Innovations for EMI Reduction in Power Supplies](#)
  - Texas Instruments, [Valuing Wide  \$V\_{IN}\$ , Low EMI Synchronous Buck Circuits for Cost-driven, Demanding Applications](#)
- Texas Instruments, [Improve High-Current DC/DC Regulator EMI for Free With Optimized Power Stage Layout application brief](#)
- Texas Instruments, [Reduce Buck Converter EMI and Voltage Stress by Minimizing Inductive Parasitics analog design journal](#)

### 5.2.1.2 Thermal Design Resources

- Texas Instruments, [Improving Thermal Performance in High Ambient Temperature Environments With Thermally Enhanced Packaging white paper](#)
- Applications notes:
  - Texas Instruments, [Thermal Design by Insight, Not Hindsight](#)
  - Texas Instruments, [A Guide to Board Layout for Best Thermal Resistance for Exposed Pad Packages](#)
  - Texas Instruments, [Semiconductor and IC Package Thermal Metrics](#)
  - Texas Instruments, [PowerPAD™ Thermally Enhanced Package](#)
  - Texas Instruments, [Using New Thermal Metrics](#)
- Texas Instruments, [PowerPAD™ Made Easy application brief](#)

### 5.2.1.3 PCB Layout Resources

- LM5137F-Q1-EVM12V and LM25137F-Q1-EVM5D3 [Altium layout](#) source files
- Texas Instruments, [AN-1149 Layout Guidelines for Switching Power Supplies application note](#)
- Texas Instruments, [Improve High-Current DC/DC Regulator EMI Performance for Free With Optimized Power Stage Layout application brief](#)
- Texas Instruments, [Constructing Your Power Supply – Layout Considerations seminar](#)

## 5.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](#). Click on [Notifications](#) to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

## 5.4 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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## 5.6 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## 5.7 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 6 Revision History

DATE	REVISION	NOTES
December 2025	*	Initial Release

## 7 Mechanical, Packaging, and Orderable Information

The following pages show mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">LM25137F2RHAR</a>	Active	Production	VQFN (RHA)   36	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 150	25137F2 RHAR
<a href="#">LM25137F3RHAR</a>	Active	Production	VQFN (RHA)   36	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 150	25137F3 RHAR

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

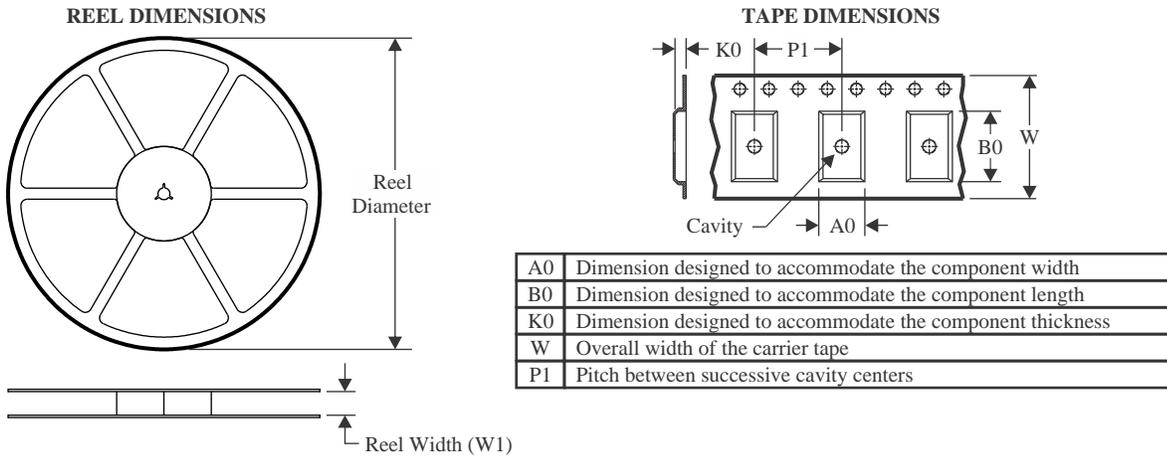
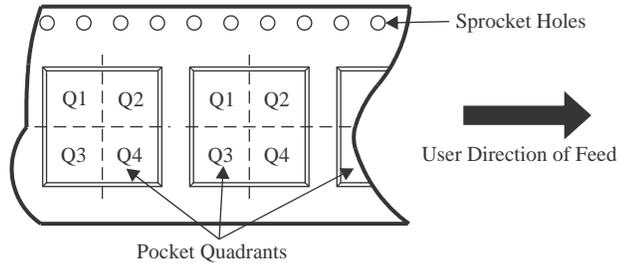
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF LM25137F :**

- Automotive : [LM25137F-Q1](#)

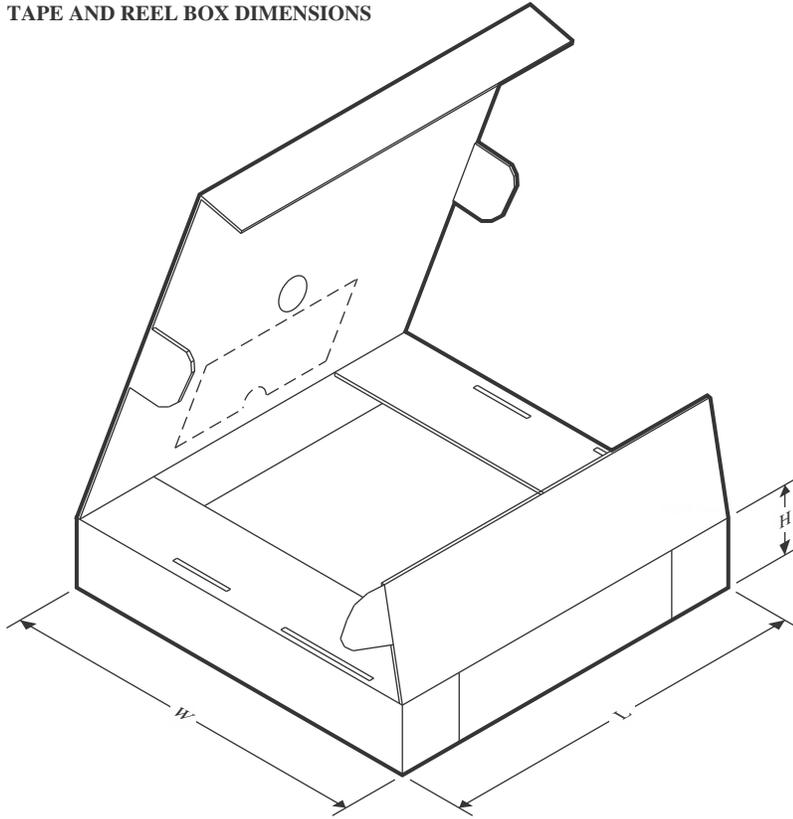
NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM25137F2RHAR	VQFN	RHA	36	2500	330.0	16.4	6.3	6.3	1.1	12.0	16.0	Q2
LM25137F3RHAR	VQFN	RHA	36	2500	330.0	16.4	6.3	6.3	1.1	12.0	16.0	Q2

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM25137F2RHAR	VQFN	RHA	36	2500	367.0	367.0	38.0
LM25137F3RHAR	VQFN	RHA	36	2500	367.0	367.0	38.0

## GENERIC PACKAGE VIEW

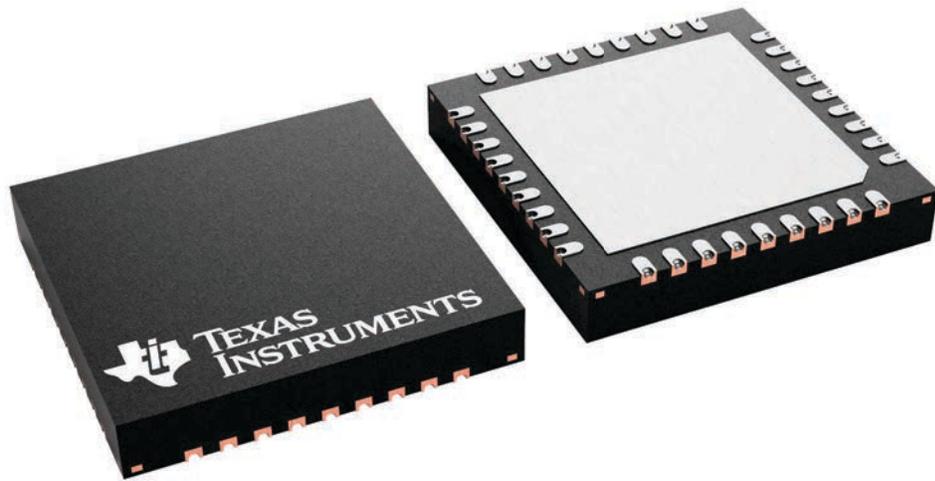
**RHA 36**

**VQFN - 1 mm max height**

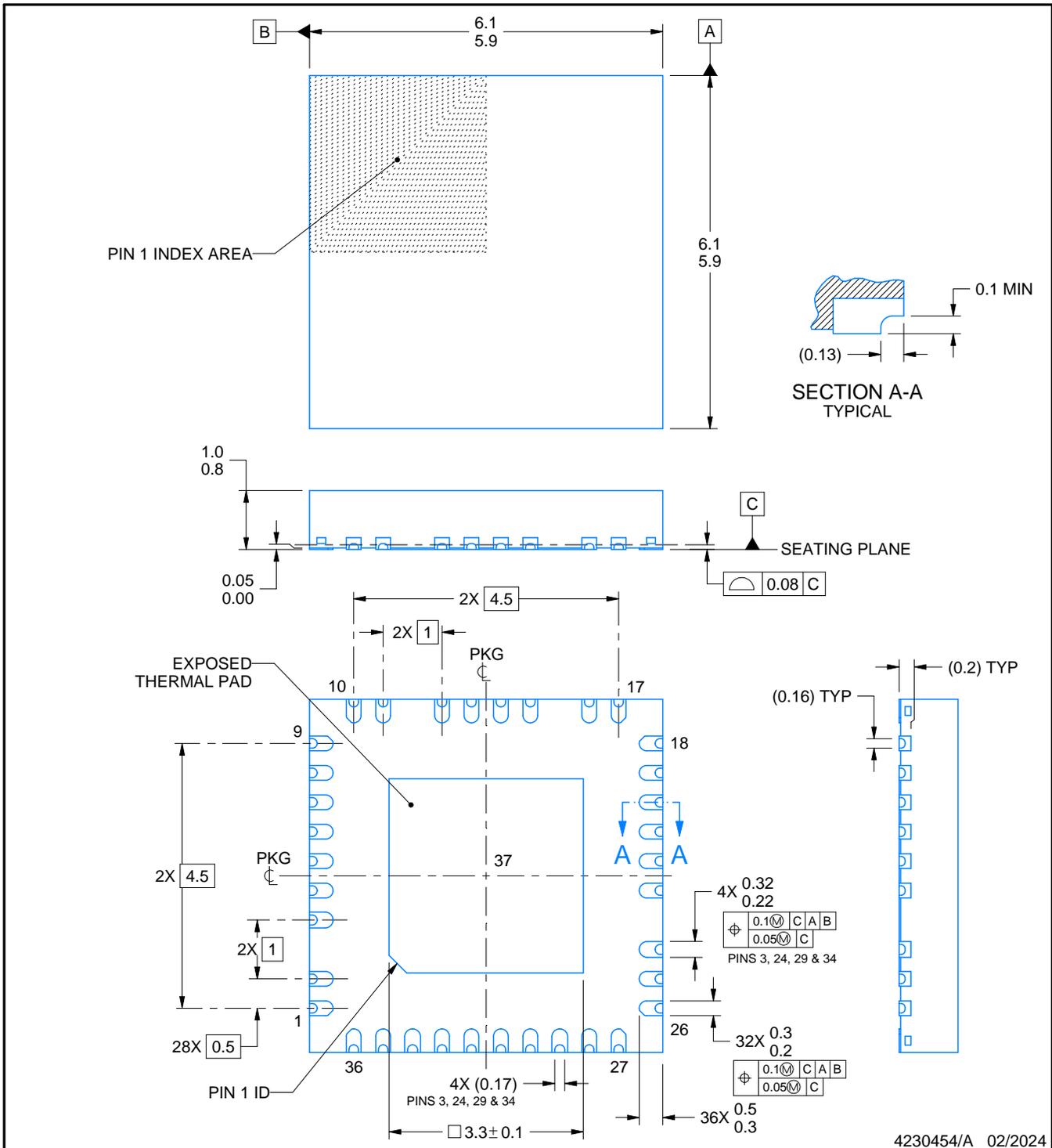
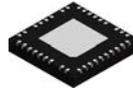
6 x 6, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



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NOTES:

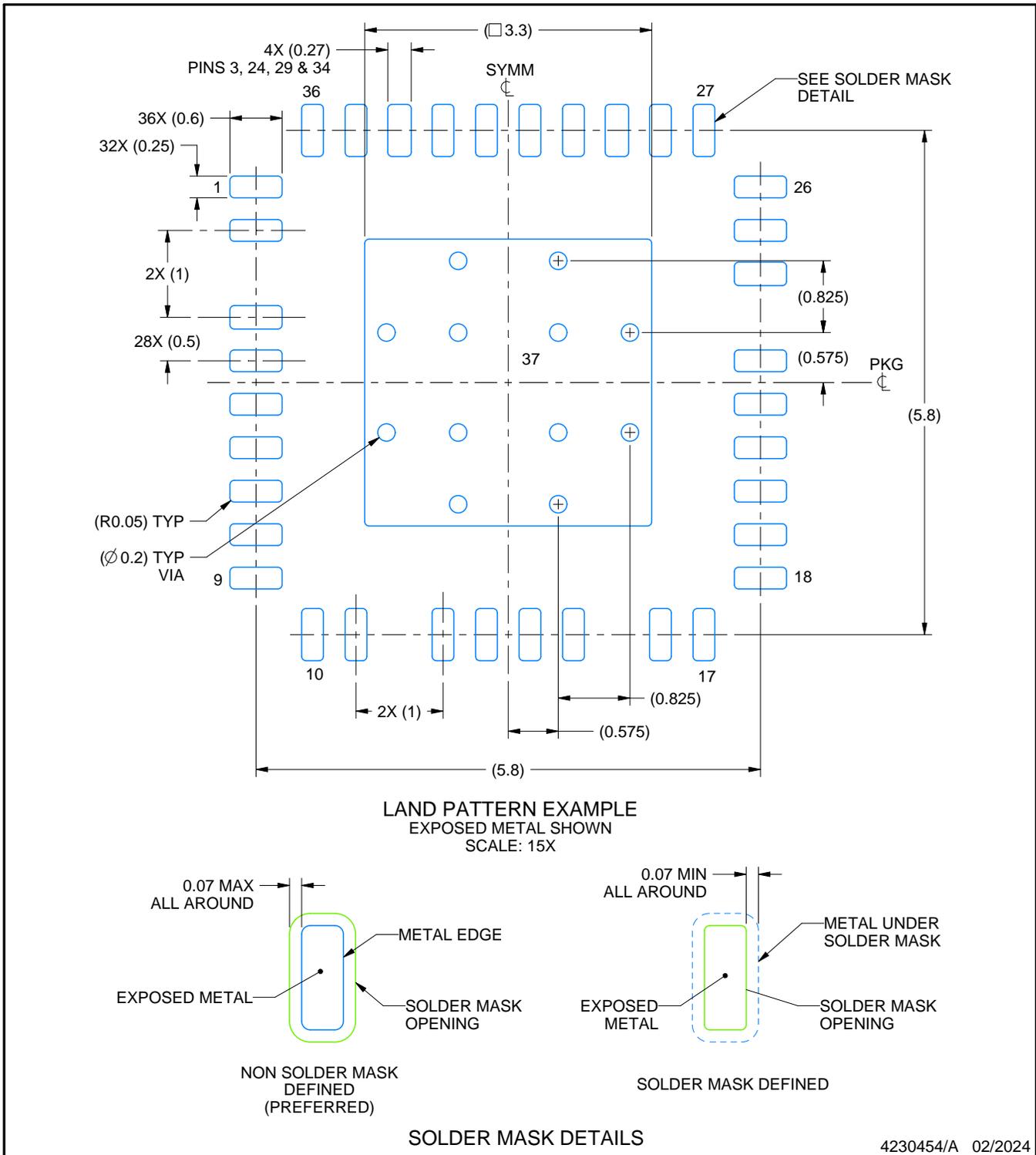
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

RHA0036D

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



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NOTES: (continued)

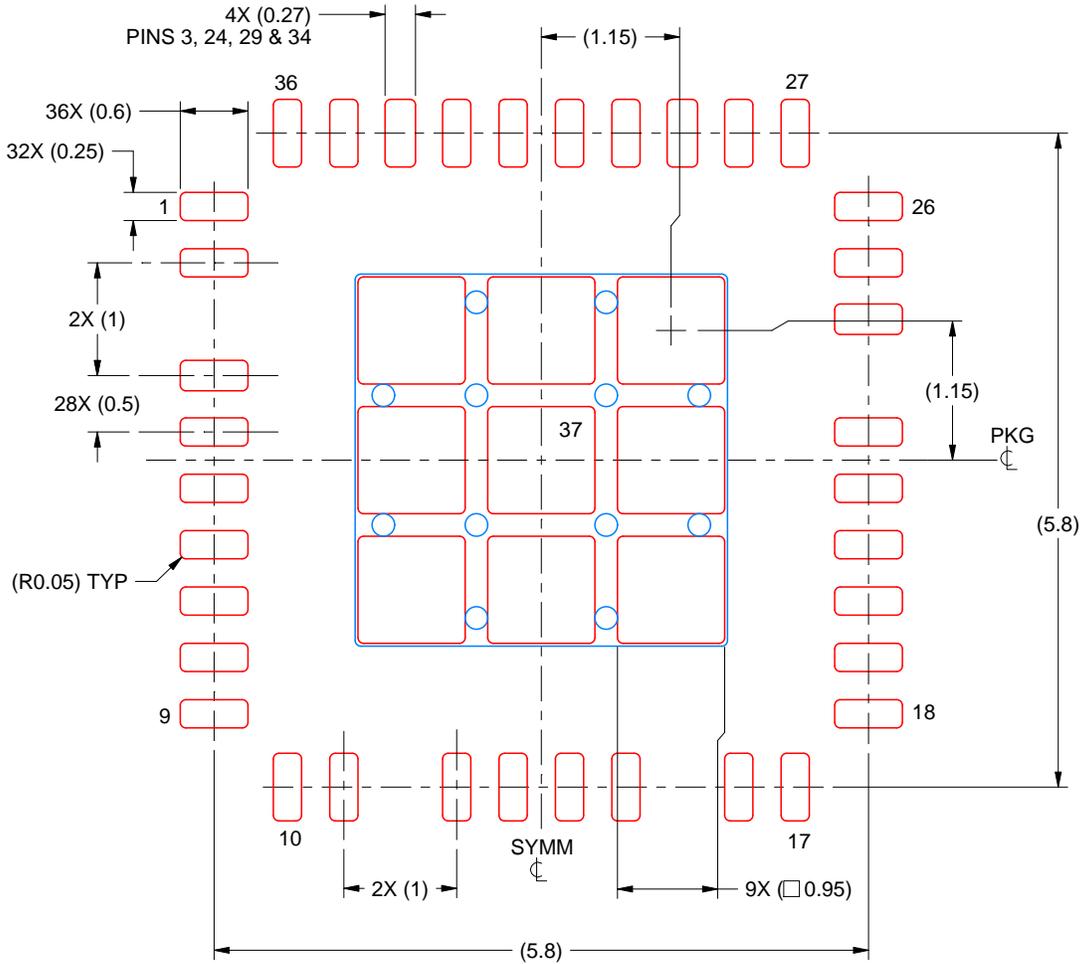
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

RHA0036D

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
 BASED ON 0.125 MM THICK STENCIL  
 SCALE: 15X

EXPOSED PAD 37  
 75% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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